

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2% Zener Voltage Tolerance SMD Zener Diode

FEATURES

- Wide zener voltage range selection: 5.1V to 20V
- VZ Tolerance Selection of ± 2%
- Surface device type mountin
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

Constant Voltage control

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- Case: SOD-523F
- Molding compound meets UL 94 V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- · Polarity: Indicated by cathode band
- Weight: 1.3mg ± 20 %

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
V _Z	5.1-20	V			
Test current I _{ZT}	5	mA			
P _{tot}	150	mW			
T _J Max.	150	°C			
Package	SOD-	523F			
Configuration	Single	dice			







ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)						
PARAMETER	SYMBOL	VALUE	UNIT			
Total power dissipation	P _{tot}	150	mW			
Junction temperature range	TJ	-55 to +150	°C			
Storage temperature range	T _{STG}	-55 to +150	°C			

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	833	°C/W

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ELECTR	ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)											
			ZENEI VOLTA(2	TEST CURRENT	REG	ULAR DANCE	TEST CURRENT	LEAR		TYPIC TEMPERA COEFFIC	ATURE
PART NUMBER	CODE		V _z @ I _z	т	I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{zk} @	I _{zk}	I _R @) V _R	T _c @I	ZT
			٧		mA	Ω	Ω	mA	μΑ	V	mV/°	С
		Min.	Nom.	Max.		Max.	Max.		Max.		Min.	Max.
BZX584B5V1	2Z2	5.00	5.1	5.20	5	60	480	1	2	2.0	-2.7	1.2
BZX584B5V6	2Z3	5.49	5.6	5.71	5	40	400	1	1	2.0	-2.0	2.5
BZX584B6V2	2Z4	6.08	6.2	6.32	5	10	150	1	3	4.0	0.4	3.7
BZX584B6V8	2Z5	6.66	6.8	6.94	5	15	80	1	2	4.0	1.2	4.5
BZX584B7V5	2Z6	7.35	7.5	7.65	5	15	80	1	1	5.0	2.5	5.3
BZX584B8V2	2Z7	8.04	8.2	8.36	5	15	80	1	0.7	5.0	3.2	6.2
BZX584B9V1	2Z8	8.92	9.1	9.28	5	15	100	1	0.5	6.0	3.8	7.0
BZX584B10	2Z9	9.80	10	10.20	5	20	150	1	0.2	7.0	4.5	8.0
BZX584B11	2Y1	10.78	11	11.22	5	20	150	1	0.1	8.0	5.4	9.0
BZX584B12	2Y2	11.76	12	12.24	5	25	150	1	0.1	8.0	6.0	10.0
BZX584B13	2Y3	12.74	13	13.26	5	30	170	1	0.1	8.0	7.0	11.0
BZX584B15	2Y4	14.70	15	15.30	5	30	200	1	0.1	10.5	9.2	13.0
BZX584B16	2Y5	15.68	16	16.32	5	40	200	1	0.1	11.2	10.4	14.0
BZX584B18	2Y6	17.64	18	18.36	5	45	225	1	0.1	12.6	12.4	16.0
BZX584B20	2Y7	19.60	20	20.40	5	55	225	1	0.1	14.0	14.4	18.0

ORDERING INFORMATION					
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
BZX584Bxxx (Note1&2)	RS	G	SOD-523F	8K / 7" Reel	

Notes:

- 1. "xxx" defines voltage from 5.1V (BZX584B5V1) to 20V (BZX584B20)
- 2. Whole series with green compound

EXAMPLE				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
BZX584B5V1 RSG	BZX584B5V1	RS	G	Green compound

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CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Typical Forward Characteristics

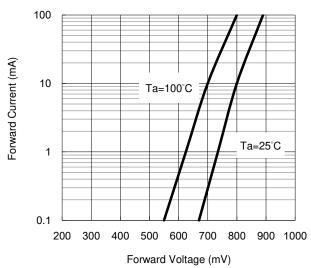


Fig. 2 Reverse Current vs Reverse Voltage

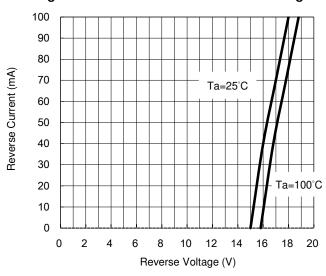


Fig.3 Admissible Power Dissipation Curve

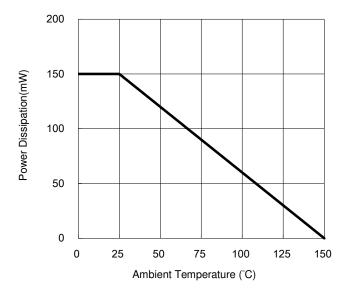
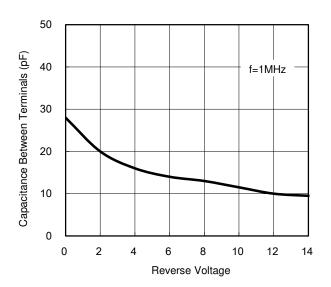
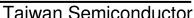


Fig.4 Typical Capacitance Characteristics

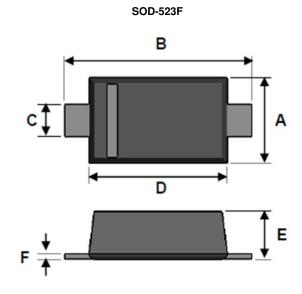


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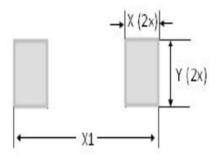


PACKAGE OUTLINE DIMENSION



	Unit(mm)	Unit(inch)		
DIM.	Min	Max	Min	Max	
А	0.70	0.90	0.028	0.035	
В	1.50	1.70	0.059	0.067	
С	0.25	0.40	0.010	0.016	
D	1.10	1.30	0.043	0.051	
E	0.50	0.77	0.020	0.030	
F	0.07	0.20	0.003	0.008	

SUGGEST PAD LAYOUT



DIM	Unit(mm)	Unit(inch)	
DIM.	Тур.	Тур.	
Х	0.60	0.024	
X1	2.30	0.091	
Υ	0.80	0.031	



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